



WS72412

18MHz Rail-to-Rail Input Output CMOS Operational Amplifiers

Descriptions

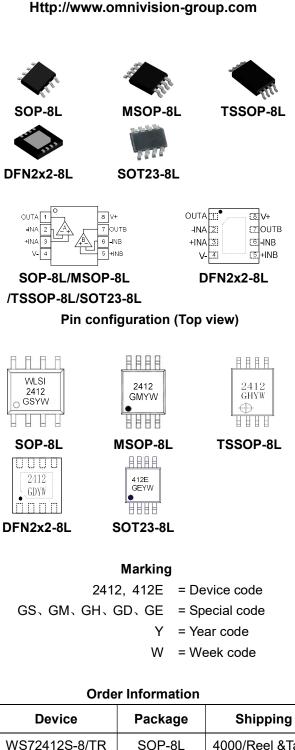
The WS72412 is a low power rail-to-rail input output operational amplifier featuring low current noise, high slew rate and wide signal bandwidth. The combination of low noise, low input bias currents, high speed and inside EMI filter make this amplifier useful in a wide variety of applications. Filters, integrators, photo-diode amplifiers, and high impedance sensors all benefit from this combination of performance features. Audio and other ac applications benefit from the wide bandwidth and low distortion of this device. Applications for this amplifier include power amplifier (PA) controls, laser diode control loops, portable and loop-powered instrumentation, audio amplification for portable devices, and ASIC input and output amplifiers. The WS72412 is dual channel version available in SOP-8L, MSOP-8L, TSSOP-8L, DFN2x2-8L and SOT23-8L package.

Applications

- Sensor Signal Conditioning
- Consumer Audio
- Multi-Pole Active Filters
- Communications
- Scanners

Features

- Gain-bandwidth Product : 18 MHz
- Low Noise : 8 nV/ √ Hz(f= 1kHz)
- Slew Rate : 9 V/µs
- Offset Voltage : 2.5 mV (max)
- Supply Range : 2.2 V to 5.5 V
- Supply Current : 1.25 mA/ch
- High Output Current : 170 mA
- Low THD+N : -102 dB
- Rail-to-Rail Input/Output Swing
- 40°C to 125°C Operation Range
- Robust 8kV HBM and 400V MM and 2kV CDM



Device	I ackage	Shipping
WS72412S-8/TR	SOP-8L	4000/Reel &Tape
WS72412M-8/TR	MSOP-8L	4000/Reel &Tape
WS72412H-8/TR	TSSOP-8L	4000/Reel &Tape
WS72412D-8/TR	DFN2x2-8L	3000/Reel &Tape
WS72412E-8/TR	SOT23-8L	3000/Reel &Tape



Pin Descriptions

Pin Number	Symbol	Descriptions	
1	OUTA	Output of Amplifier A	
2	-INA	Inverting input of Amplifier A	
3	+INA	Non-inverting input of Amplifier A	
4	V-	Negative supply	
5	+INB	Non-inverting input of Amplifier B	
6	-INB	Inverting input of Amplifier B	
7	OUTB	Output of Amplifier B	
8	V+	Positive supply	

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Supply Voltage, ([V+] – [V-])	V _S ⁽²⁾	6	V
Input Differential Voltage	$V_{IDR}^{(3)}$	±6	V
Input Common Mode Voltage Range	V _{ICR}	(V-)-0.2 to (V+)+0.2	V
Output Short-Circuit Duration	t _{so}	Unlimited	/
Operating Fee-Air Temperature Range	T _A	-40 to 125	°C
Storage Temperature Range	T _{STG}	-65 to 150	°C
Junction Temperature Range	TJ	150	°C
Lead Temperature Range	TL	260	°C

Note:

- Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are only stress ratings, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions are not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- 2. All voltage values, except differential voltage are with respect to network terminal.
- 3. Differential voltages are at +IN with respect to -IN.

ESD, Electrostatic Discharge Protection

Symbol	Parameter	ameter Condition		Unit	
НВМ	Human Body Model ESD	MIL-STD-883H Method 3015.8	±8000	v	
		JEDEC-EIA/JESD22-A114A	_0000		
MM	Machine Model ESD	JEDEC-EIA/JESD22-A115	±400	V	
CDM	Charged Device Model ESD	JEDEC-EIA/JESD22-C101E	±2000	V	



Electronics Characteristics

At $T_A = 25^{\circ}C$, $V_S = 5V$, $V_{CM} = V_{OUT} = V_S/2$, $R_{load} = 100k\Omega$, $C_{load} = 100pF$, unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
V _{OS}	Input Offset Voltage	$V_{CM} = V_S/2$	-2.5	±0.6	+2.5	mV
α_{VOS}	Input Offset Voltage Drift	-40°C to 125°C		2		μV/°C
I _{IB}	Input Bias Current			10		pА
l _{os}	Input Offset Current			10		pА
V _n	Input Voltage Noise	f=0.1Hz to10Hz		0.6		μV _{P-P}
en	Input Voltage Noise Density	f=1kHz		8		nV/√Hz
CMRR	Common Mode Rejection Ratio	V _{CM} =1V to 3V	60	105		dB
V _{CM}	Common Mode Input Voltage Range		(V-)-0.1		(V+)+0.1	V
PSRR	Power Supply Rejection Ratio	$V_{\rm S}$ = 2.2V to 5.5V, $V_{\rm CM}$ = 0V	60	110		dB
A _{VOL}	Open Loop Large Signal Gain	V_{OUT} = -2V to 2V, R_{load} = 2k Ω	90	110		dB
		$R_{load}=2k\Omega$		9		mV
V _{OH}	High Level Output Voltage	R_{load} =10k Ω		2		mV
M		$R_{load}=2k\Omega$		8		mV
V _{OL}	Low Level Output Voltage	R_{load} =10k Ω		2		mV
R _{OUT}	Closed-Loop Output Impedance	G = 1, f =1MHz, I _{OUT} = 0		0.2		Ω
		Source Current		210		mA
I _{SC}	Output Short-Circuit Current	Sink Current		170		mA
Vs	Supply Voltage		2.2		5.5	V
l _Q	Quiescent Current per Amplifier	Vs=5V		1.25	1.6	mA
PM	Phase Margin	R_{load} =1k Ω , C_{load} =60pF		60		degrees
GM	Gain Margin	R_{load} =1k Ω , C_{load} =60pF		8		dB
GBWP	Gain-Bandwidth Product	f=1kHz		18		MHz
t _s	0.1% Settling Time	1.5 to 3.5V, Unity Gain		0.4		μS
SR	Slew Rate	A _V =1, R _{load} =2kΩ, C _{load} =100pF		9		V/µs
FPBW	Full Power Bandwidth	2V _{P-P}		1.4		MHz
THD+N	Total Harmonic Distortion and Noise	f=1kHz, AV=1, R_{load} =2k Ω , V_{OUT} =1 V_{PP}		-102		dB
X _{talk}	Channel Separation	$f = 1$ kHz, RL = 2k Ω		110		dB

Note:

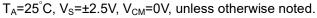
1. Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.



- 2. A heat sink may be required to keep the junction temperature below the absolute maximum rating when the output is shorted indefinitely.
- 3. Thermal resistance varies with the amount of PC board metal connected to the package. The specified values are for short traces connected to the leads.
- 4. Full power bandwidth is calculated from the slew rate FPBW = SR/($\pi \cdot V_{P-P}$).

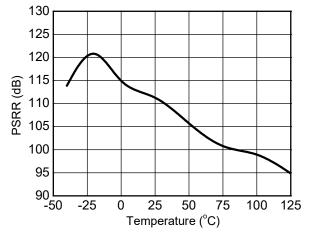


Typical Characteristics

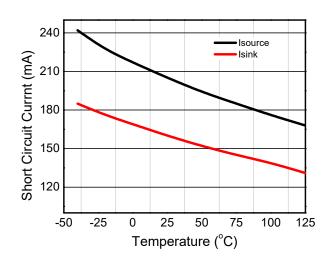


Offset Voltage Production Distribution

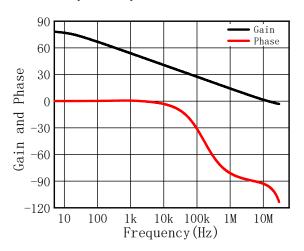
Power-Supply Rejection Ratio vs. Temperature



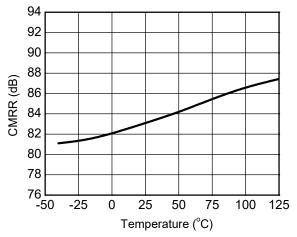
Short Circuit Current vs. Temperature

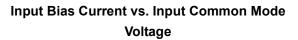


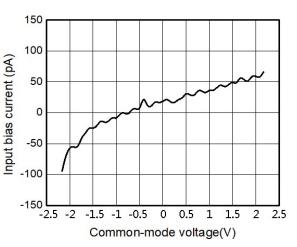
Open-Loop Gain and Phase



CMRR vs. Temperature





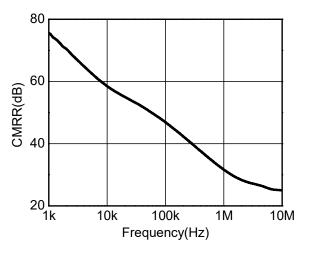




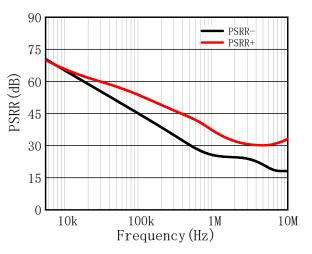
Typical Characteristics (continued)

 $T_{A}\text{=}25^{^{\circ}}\text{C},~V_{S}\text{=}\pm2.5\text{V},~V_{\text{CM}}\text{=}0\text{V},$ unless otherwise noted

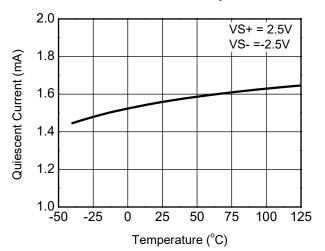
CMRR vs. Frequency



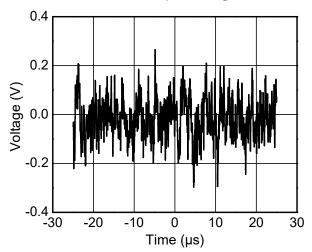
Power-Supply Rejection Ratio vs. Frequency



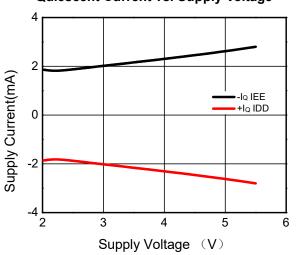
Quiescent Current vs. Temperature

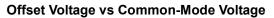


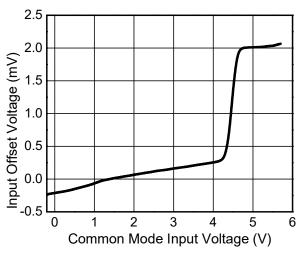
0.1 Hz TO 10 Hz Input Voltage Noise



Quiescent Current vs. Supply Voltage





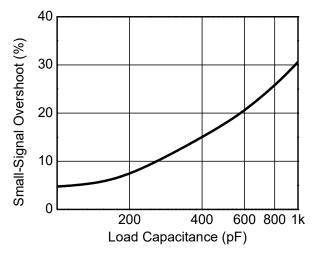




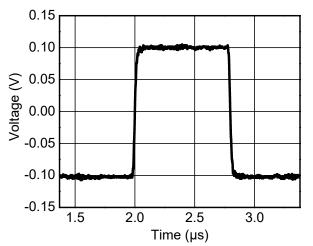
Typical Characteristics (continued)

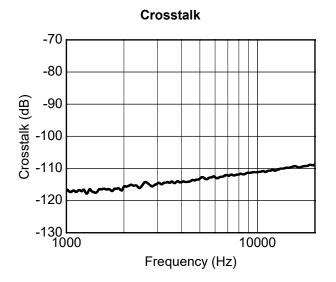
 $T_{A}\text{=}25^{^{\circ}}\text{C},~V_{S}\text{=}\pm2.5\text{V},~V_{\text{CM}}\text{=}0\text{V},$ unless otherwise noted

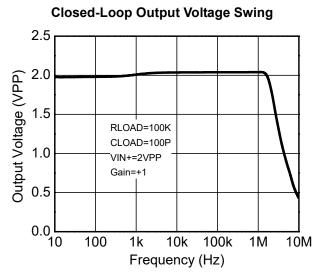
Small-Signal Overshoot vs. Load Capacitance



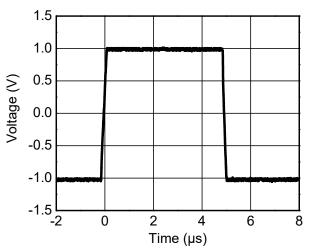




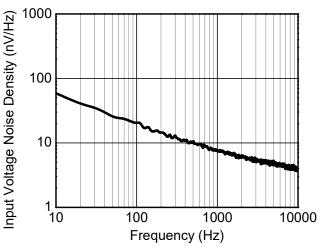




Large-Scale Step Response, 2V Step



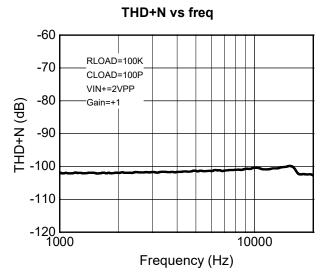


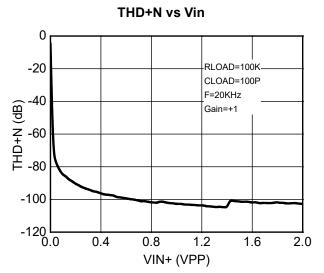




Typical Characteristics (continued)

 $T_{A}\text{=}25^{^{\circ}}\text{C},\,V_{S}\text{=}\pm2.5\text{V},\,V_{CM}\text{=}0\text{V},\,\text{unless otherwise noted}$





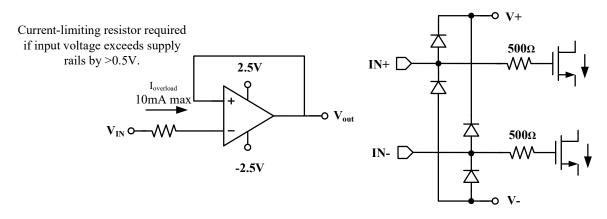


Operation

The WS72412 series op amps can operate on a single-supply voltage (2.2 V to 5.5 V), or a split-supply voltage (\pm 1.1 V to \pm 2.75 V), making them highly versatile and easy to use. The power-supply pins should have local bypass ceramic capacitors (typically 0.001 µF to 0.1 µF). These amplifiers are fully specified from +2.2 V to +5.5 V and over the extended temperature range of -40°C to +125°C. Parameters that can exhibit variance with regard to operating voltage or temperature are presented in the Typical Characteristics.

Input ESD Diode Protection

The WS72412 incorporates internal electrostatic discharge (ESD) protection circuits on all pins. In the case of input and output pins, this protection primarily consists of current-steering diodes connected between the input and power-supply pins. These ESD protection diodes also provide in-circuit input overdrive protection, as long as the current is limited to 10 mA as stated in the Absolute Maximum Ratings table. Many input signals are inherently current-limited to less than 10 mA; therefore, a limiting resistor is not required. Figure 1 shows how a series input resistor (RS) may be added to the driven input to limit the input current. The added resistor contributes thermal noise at the amplifier input and the value should be kept to the minimum in noise-sensitive applications.



INPUT ESD DIODE CURRENT LIMITING- UNITY GAIN

Figure 1. Input ESD Diode

PCB Surface Leakage

In applications where low input bias current is critical, Printed Circuit Board (PCB) surface leakage effects need to be considered. Surface leakage is caused by humidity, dust or other contamination on the board. Under low humidity conditions, a typical resistance between nearby traces is 1012Ω . A 5V difference would cause 5pA of current to flow, which is greater than the WS72412 OPA' s input bias current at +27° C (±3pA, typical). It is recommended to use multi-layer PCB layout and route the OPA' s -IN and +IN signal under the PCB surface.

The effective way to reduce surface leakage is to use a guard ring around sensitive pins (or traces). The guard ring is biased at the same voltage as the sensitive pin. An example of this type of layout is shown in Figure 1 for Inverting Gain application.

1. For Non-Inverting Gain and Unity-Gain Buffer:



a) Connect the non-inverting pin (VIN+) to the input with a wire that does not touch the PCB surface.

 b) Connect the guard ring to the inverting input pin (VIN–). This biases the guard ring to the Common Mode input voltage.

2. For Inverting Gain and Trans-impedance Gain Amplifiers (convert current to voltage, such as photo detectors):

a) Connect the guard ring to the non-inverting input pin (VIN+). This biases the guard ring to the same reference voltage as the op-amp (e.g., VDD/2 or ground).

b) Connect the inverting pin (VIN–) to the input with a wire that does not touch the PCB surface.

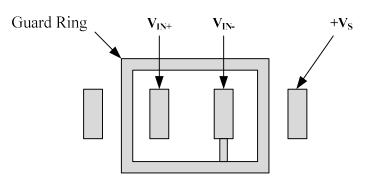


Figure 2. The Layout of Guard Ring

Power Supply Layout and Bypass

The WS72412 OPA's power supply pin (VDD for single-supply) should have a local bypass capacitor (i.e., 0.01μ F to 0.1μ F) within 2mm for good high frequency performance. It can also use a bulk capacitor (i.e., 1μ F or larger) within 100mm to provide large, slow currents. This bulk capacitor can be shared with other analog parts.

Ground layout improves performance by decreasing the amount of stray capacitance and noise at the OPA's inputs and outputs. To decrease stray capacitance, minimize PC board lengths and resistor leads, and place external components as close to the op amps' pins as possible.

Proper Board Layout

To ensure optimum performance at the PCB level, care must be taken in the design of the board layout. To avoid leakage currents, the surface of the board should be kept clean and free of moisture. Coating the surface creates a barrier to moisture accumulation and helps reduce parasitic resistance on the board.

Keeping supply traces short and properly bypassing the power supplies minimizes power supply disturbances due to output current variation, such as when driving an ac signal into a heavy load. Bypass capacitors should be connected as closely as possible to the device supply pins. Stray capacitances are a concern at the outputs and the inputs of the amplifier. It is recommended that signal traces be kept at least 5mm from supply lines to minimize coupling.

A variation in temperature across the PCB can cause a mismatch in the Seebeck voltages at solder joints and other points where dissimilar metals are in contact, resulting in thermal voltage errors. To minimize these thermocouple effects, orient resistors so heat sources warm both ends equally. Input signal paths should



contain matching numbers and types of components, where possible to match the number and type of thermocouple junctions. For example, dummy components such as zero value resistors can be used to match real resistors in the opposite input path. Matching components should be located in close proximity and should be oriented in the same manner. Ensure leads are of equal length so that thermal conduction is in equilibrium. Keep heat sources on the PCB as far away from amplifier input circuitry as is practical.

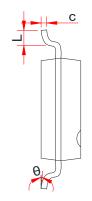
The use of a ground plane is highly recommended. A ground plane reduces EMI noise and also helps to maintain a constant temperature across the circuit board.



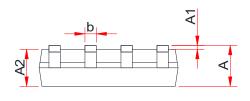
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SOP-8L



TOP VIEW



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SIDE VIEW

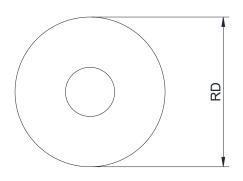
SIDE VIEW

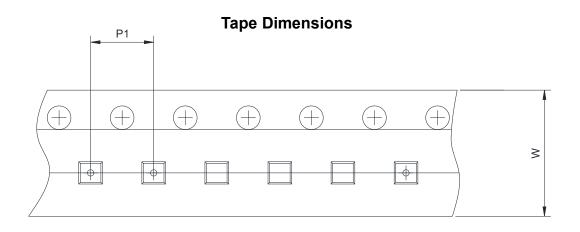
Symbol	Dime	Dimensions In Millimeters (mm)				
Symbol	Min.	Тур.	Max.			
A	1.35	1.55	1.75			
A1	0.05	0.15	0.25			
A2	1.25	1.40	1.65			
b	0.33	-	0.51			
с	0.15	-	0.26			
D	4.70	4.90	5.10			
E	3.70	3.90	4.10			
E1	5.80	6.00	6.20			
е		1.27BSC				
L	0.40	-	1.27			
θ	0°	-	8°			



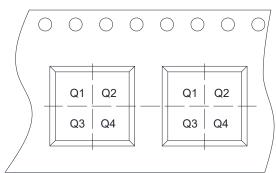
SOP-8L

Reel Dimensions





Quadrant Assignments For PIN1 Orientation In Tape

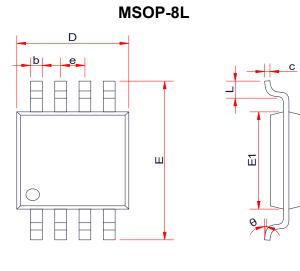




User Direction of Feed

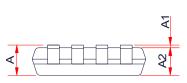
RD	Reel Dimension	🔲 7inch	🔽 13inch		
W	Overall width of the carrier tape	🔲 8mm	🔽 12mm		
P1	Pitch between successive cavity centers	🔲 2mm	🔲 4mm	🔽 8mm	
Pin1	Pin1 Quadrant	🔽 Q1	🔲 Q2	Q3	🔲 Q4





TOP VIEW

SIDE VIEW



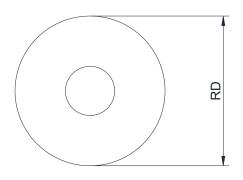
SIDE VIEW

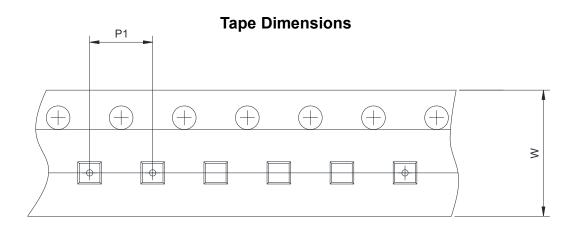
Symbol	Dimens	Dimensions In Millimeters (mm)				
	Min.	Min. Typ.				
A	-	-	1.10			
A1	0.02	-	0.15			
A2	0.75	0.80	0.95			
b	0.25	-	0.38			
с	0.09	-	0.23			
D	2.90	3.00	3.10			
E	4.75	4.90	5.05			
E1	2.90	3.00	3.10			
е		0.65 BSC				
L	0.40	0.40 - 0.80				
θ	0°	-	6°			



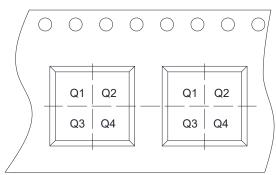
MSOP-8L

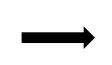
Reel Dimensions





Quadrant Assignments For PIN1 Orientation In Tape



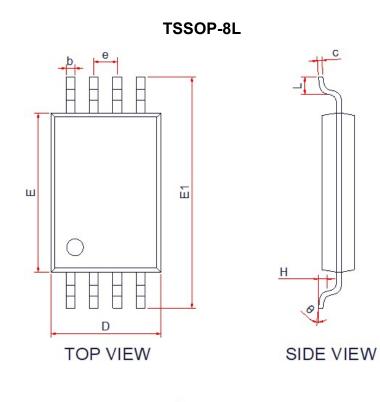


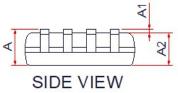
User Direction of Feed

RD	Reel Dimension	🔲 7inch	🔽 13inch		
W	Overall width of the carrier tape	🔲 8mm	🔽 12mm		
P1	Pitch between successive cavity centers	🔲 2mm	🔲 4mm	🔽 8mm	
Pin1	Pin1 Quadrant	🔽 Q1	🗖 Q2	C Q3	🔲 Q4

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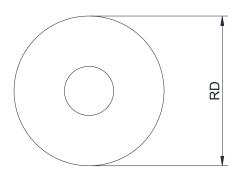


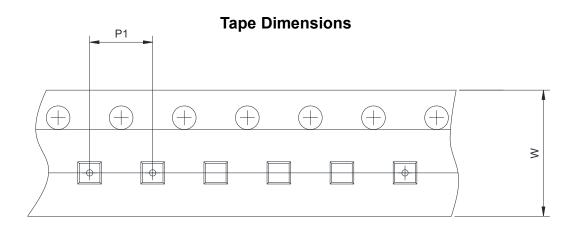
Symbol	Dimensions In Millimeters (mm)					
	Min.	Min. Typ.				
А	-	-	1.20			
A1	0.05	-	0.15			
A2	0.80	-	1.05			
b	0.19	-	0.30			
с	0.09	-	0.20			
D	2.90	3.00	3.10			
E	4.30	4.40	4.50			
E1	6.25	6.40	6.55			
е		0.65 BSC				
L	0.45	-	0.75			
θ	0°	-	8°			



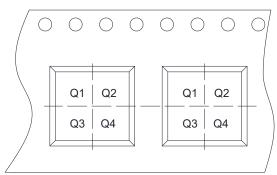
TSSOP-8L

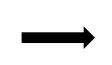
Reel Dimensions





Quadrant Assignments For PIN1 Orientation In Tape





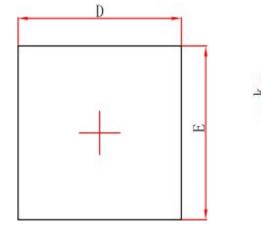
User Direction of Feed

RD	Reel Dimension	🔝 7inch	🔽 13inch		
W	Overall width of the carrier tape	🔲 8mm	🔽 12mm		
P1	Pitch between successive cavity centers	🔲 2mm	🔲 4mm	🔽 8mm	
Pin1	Pin1 Quadrant	🔽 Q1	🗖 Q2	Q3	🔲 Q4

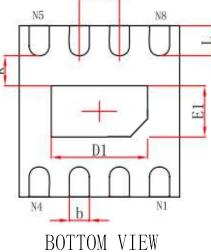
Will Semiconductor Ltd.

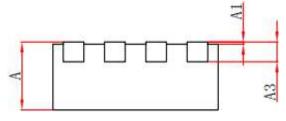






TOP VIEW





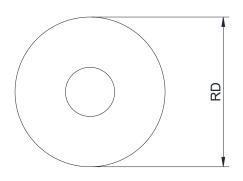
SIDE VIEW

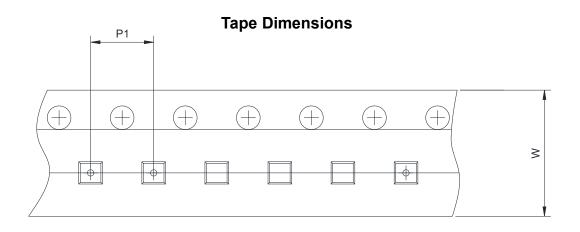
Symbol	Dimen	Dimensions In Millimeters (mm)				
	Min.	Min. Typ.				
A	0.70	0.75	0.80			
A1	0.00	0.025	0.05			
A3		0.203 REF				
D	1.90	1.90 2.00 2.10				
E	1.90	2.00	2.10			
D1	1.50	1.60	1.70			
E1	0.80	0.90	1.00			
k		0.25 REF				
b	0.20	0.20 0.25 0.30				
е		0.50 BSC				
L	0.224	0.30	0.376			



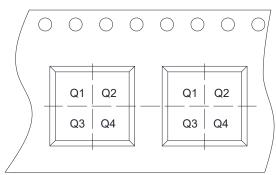
DFN2x2-8L

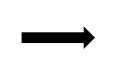
Reel Dimensions





Quadrant Assignments For PIN1 Orientation In Tape

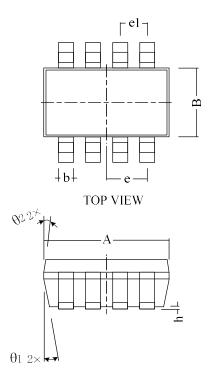




User Direction of Feed

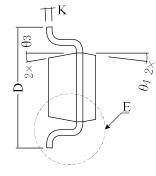
RD	Reel Dimension	🗹 7inch	🔲 13inch		
W	Overall width of the carrier tape	🔽 8mm	🔲 12mm		
P1	Pitch between successive cavity centers	🔲 2mm	🗹 4mm	🔲 8mm	
Pin1	Pin1 Quadrant	🔽 Q1	🗖 Q2	C Q3	🔲 Q4



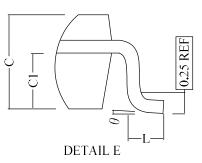


SIDE VIEW

SOT23-8L



SIDE VIEW



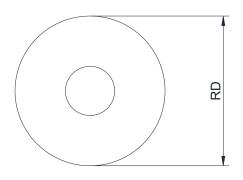
Symbol	Dimensions In Millimeters (mm)					
	Min.	Тур.	Max.			
A	2.820	2.920	3.020			
В	1.500	1.600	1.700			
С	1.050	1.100	1.150			
C1	0.600	0.650 2.800	0.700			
D	2.650		2.950			
L	0.300	0.450	0.600			
b	0.320	0.400	0.480			
h	0.020	0.050	0.100			
к	0.100		0.200			
е	0.950 TYPE					
e1	0.633 TYPE					
θ1	8° TYPE					
θ2	8° TYPE					
θ3	8° TYPE					
θ4	8° TYPE					
θ	0°~8°					

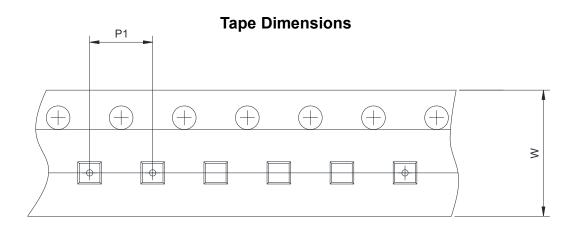
Will Semiconductor Ltd.



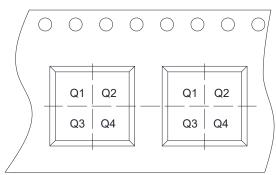
SOT23-8L

Reel Dimensions





Quadrant Assignments For PIN1 Orientation In Tape





User Direction of Feed

RD	Reel Dimension	🗹 7inch	🔲 13inch		
W	Overall width of the carrier tape	🔽 8mm	🔲 12mm		
P1	Pitch between successive cavity centers	🔲 2mm	🗹 4mm	🔲 8mm	
Pin1	Pin1 Quadrant	🗖 Q1	🗖 Q2	✓ Q3	🗖 Q4